Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	78K/0
Core Size	8-Bit
Speed	20MHz
Connectivity	3-Wire SIO, I²C, LINbus, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	71
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/upd78f0546agk-gak-ax

2.2 Description of Pin Functions

Remark The pins mounted depend on the product. See **1.4 Ordering Information** and **2.1 Pin Function List**.

2.2.1 P00 to P06 (port 0)

P00 to P06 function as an I/O port. These pins also function as timer I/O, serial interface data I/O, clock I/O, and chip select input.

	78K0/KB2	78K0/KC2	78K0/KD2	78K0/KE2		78K0/KF2
				Products whose flash memory is less than 32 KB	Products whose flash memory is at least 48 KB	
P00/TI000	√		√	√	√	
P01/TI010/TO00	√		√	√	√	
P02/SO11	–		P02Note	P02Note	√	
P03/SI11	–		P03Note	P03Note	√	
P04/$\overline{\text{SCK11}}$	–		–	P04Note	√	
P05/TI001/$\overline{\text{SSI11}}$	–		–	P05Note	√	
P06/TI011/TO01	–		–	P06Note	√	

Note The 78K0/KE2 products whose flash memory is less than 32 KB and 78K0/KD2 products are only provided with port functions and not alternate functions.

Remark √: Mounted, –: Not mounted

The following operation modes can be specified in 1-bit units.

(1) Port mode

P00 to P06 function as an I/O port. P00 to P06 can be set to input or output port in 1-bit units using port mode register 0 (PM0). Use of an on-chip pull-up resistor can be specified by pull-up resistor option register 0 (PU0).

(2) Control mode

P00 to P06 function as timer I/O, serial interface data I/O, clock I/O, and chip select input.

(a) TI000, TI001

These are the pins for inputting an external count clock to 16-bit timer/event counters 00 and 01 and are also for inputting a capture trigger signal to the capture registers (CR000, CR010 or CR001, CR011) of 16-bit timer/event counters 00 and 01.

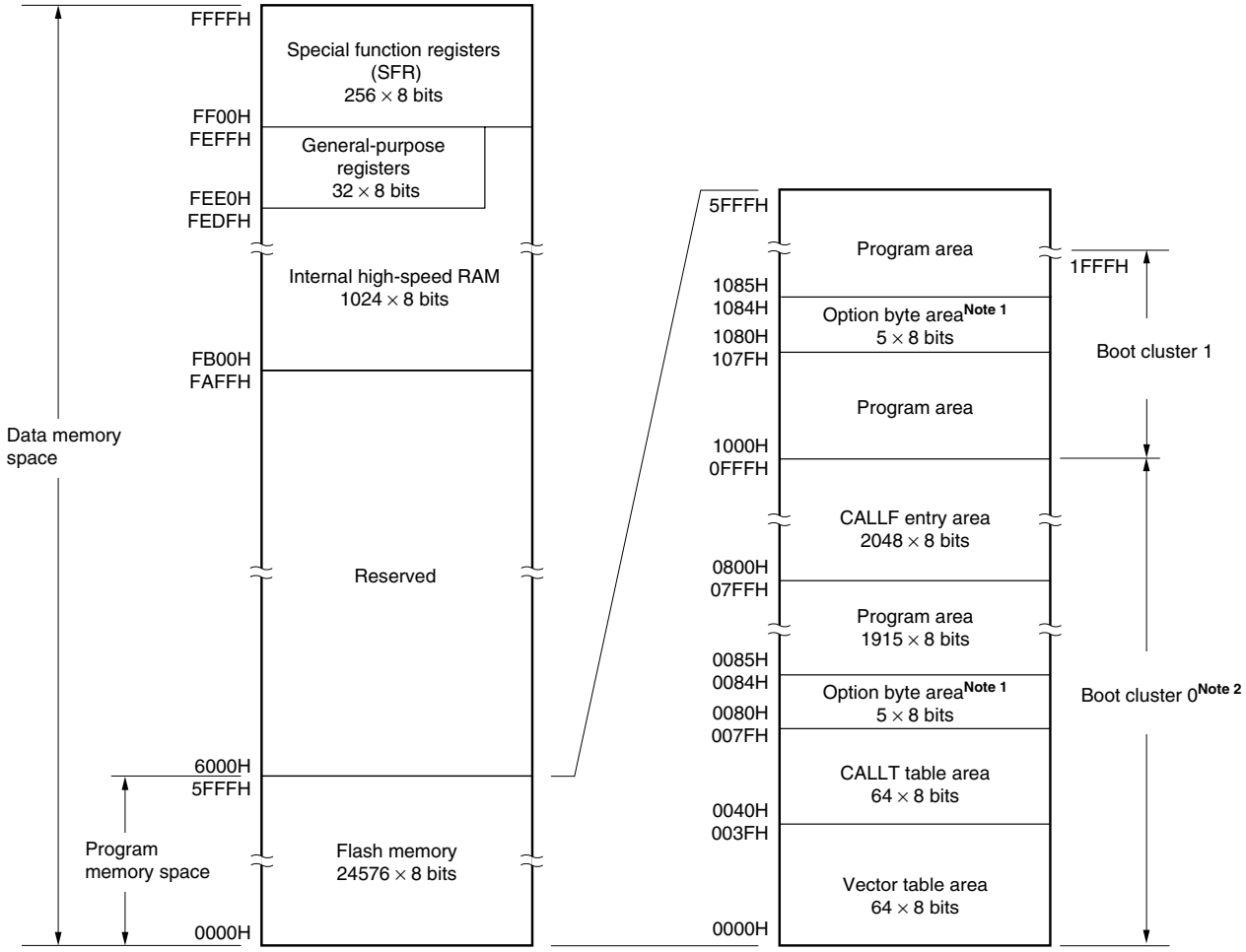
(b) TI010, TI011

These are the pins for inputting a capture trigger signal to the capture register (CR000 or CR001) of 16-bit timer/event counters 00 and 01.

(c) TO00, TO01

These are timer output pins of 16-bit timer/event counters 00 and 01.

Figure 3-3. Memory Map (μPD78F0502, 78F0502A, 78F0512, 78F0512A, 78F0522, 78F0522A, 78F0532, and 78F0532A)



Notes 1. When boot swap is not used: Set the option bytes to 0080H to 0084H.
When boot swap is used: Set the option bytes to 0080H to 0084H and 1080H to 1084H.

2. Writing boot cluster 0 can be prohibited depending on the setting of security (see **27.8 Security Settings**).

Remark The flash memory is divided into blocks (one block = 1 KB). For the address values and block numbers, see **Table 3-3 Correspondence Between Address Values and Block Numbers in Flash Memory**.

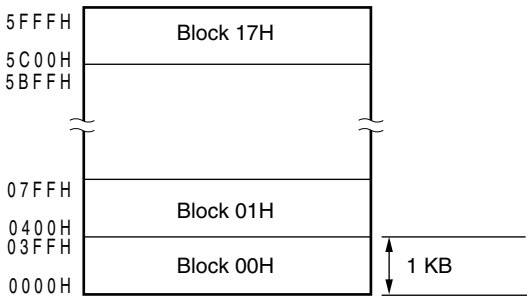
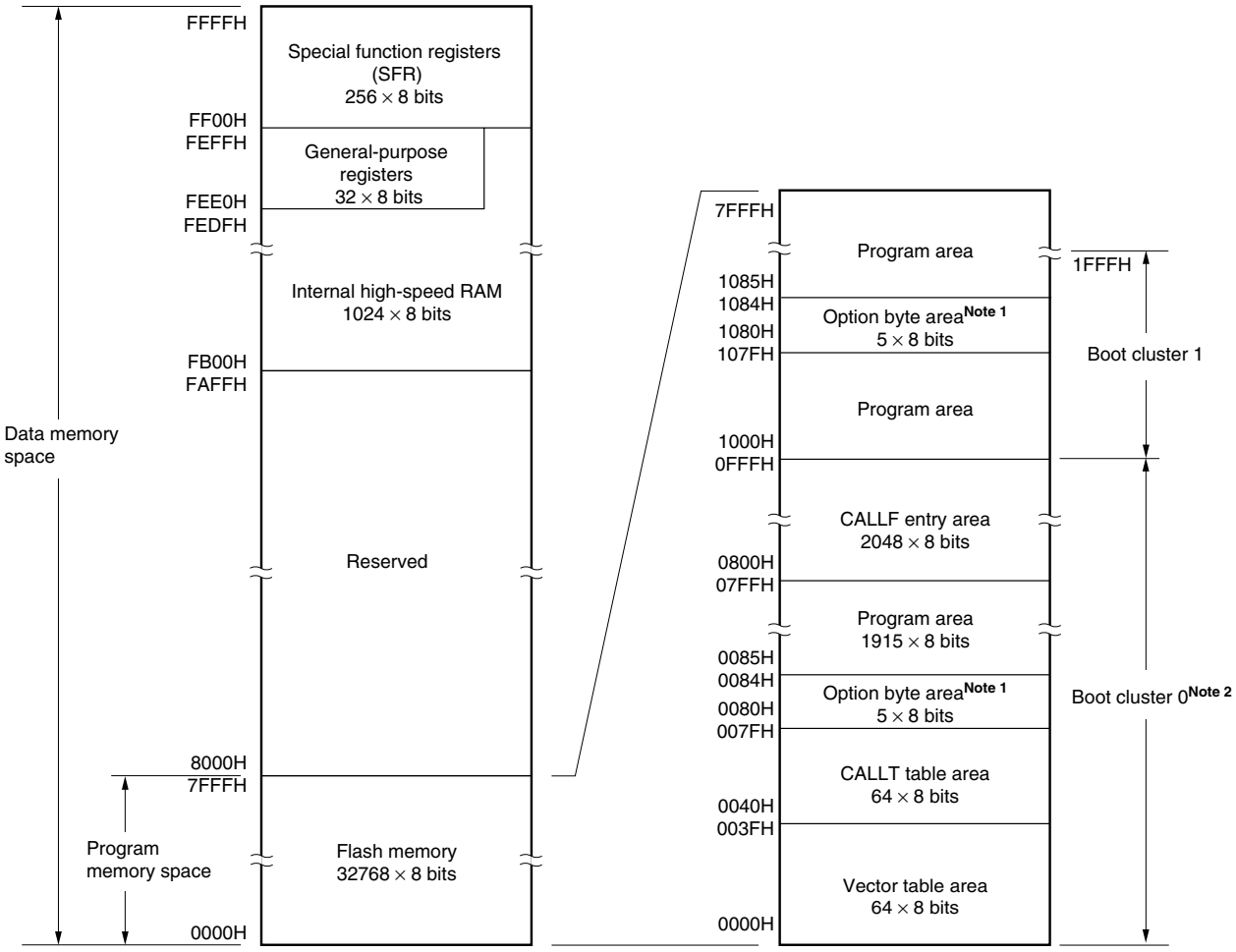


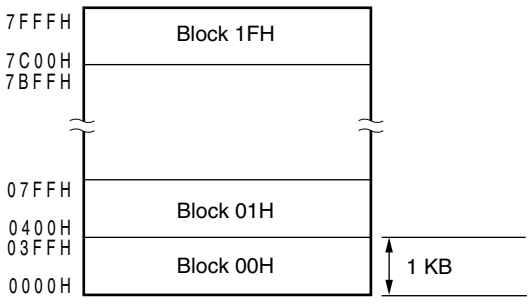
Figure 3-4. Memory Map (μPD78F0503, 78F0503A, 78F0513, 78F0513A, 78F0523, 78F0523A, 78F0533 and 78F0533A)



Notes 1. When boot swap is not used: Set the option bytes to 0080H to 0084H.
When boot swap is used: Set the option bytes to 0080H to 0084H and 1080H to 1084H.

2. Writing boot cluster 0 can be prohibited depending on the setting of security (see **27.8 Security Settings**).

Remark The flash memory is divided into blocks (one block = 1 KB). For the address values and block numbers, see **Table 3-3 Correspondence Between Address Values and Block Numbers in Flash Memory**.



(8) Oscillation stabilization time select register (OSTS)

This register is used to select the X1 clock oscillation stabilization wait time when the STOP mode is released.

When the X1 clock is selected as the CPU clock, the operation waits for the time set using OSTS after the STOP mode is released.

When the internal high-speed oscillation clock is selected as the CPU clock, confirm with OSTC that the desired oscillation stabilization time has elapsed after the STOP mode is released. The oscillation stabilization time can be checked up to the time set using OSTC.

OSTS can be set by an 8-bit memory manipulation instruction.

Reset signal generation sets OSTS to 05H.

Figure 6-11. Format of Oscillation Stabilization Time Select Register (OSTS)

Address: FFA4H After reset: 05H R/W

Symbol	7	6	5	4	3	2	1	0
OSTS	0	0	0	0	0	OSTS2	OSTS1	OSTS0

OSTS2	OSTS1	OSTS0	Oscillation stabilization time selection		
				fx = 10 MHz	fx = 20 MHz
0	0	1	2^{11}/fx	204.8 μs	102.4 μs
0	1	0	2^{13}/fx	819.2 μs	409.6 μs
0	1	1	2^{14}/fx	1.64 ms	819.2 μs
1	0	0	2^{15}/fx	3.27 ms	1.64 ms
1	0	1	2^{16}/fx	6.55 ms	3.27 ms
Other than above			Setting prohibited		

Cautions 1. To set the STOP mode when the X1 clock is used as the CPU clock, set OSTS before executing the STOP instruction.

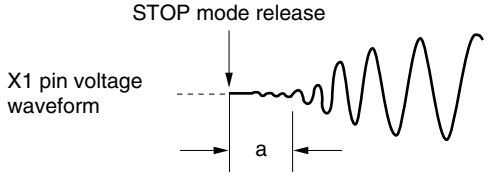
2. Do not change the value of the OSTS register during the X1 clock oscillation stabilization time.

3. The oscillation stabilization time counter counts up to the oscillation stabilization time set by OSTS. If the STOP mode is entered and then released while the internal high-speed oscillation clock is being used as the CPU clock, set the oscillation stabilization time as follows.

- **Desired OSTC oscillation stabilization time ≤ Oscillation stabilization time set by OSTS**

Note, therefore, that only the status up to the oscillation stabilization time set by OSTS is set to OSTC after STOP mode is released.

4. The X1 clock oscillation stabilization wait time does not include the time until clock oscillation starts ("a" below).



Remark fx: X1 clock oscillation frequency

6.6.7 Condition before changing CPU clock and processing after changing CPU clock

Condition before changing the CPU clock and processing after changing the CPU clock are shown below.

Table 6-7. Changing CPU Clock

	CPU Clock		Condition Before Change	Processing After Change
	Before Change	After Change		
KB2, KC2, KD2, KE2, KF2	Internal high-speed oscillation clock	X1 clock	Stabilization of X1 oscillation • MSTOP = 0, OSCSEL = 1, EXCLK = 0 • After elapse of oscillation stabilization time	• Internal high-speed oscillator can be stopped (RSTOP = 1). • Clock supply to CPU is stopped for 4.06 to 16.12 μs after AMPH has been set to 1.
		External main system clock	Enabling input of external clock from EXCLK pin • MSTOP = 0, OSCSEL = 1, EXCLK = 1	• Internal high-speed oscillator can be stopped (RSTOP = 1). • Clock supply to CPU is stopped for the duration of 160 external clocks from the EXCLK pin after AMPH has been set to 1.
	X1 clock	Internal high-speed oscillation clock	Oscillation of internal high-speed oscillator • RSTOP = 0	X1 oscillation can be stopped (MSTOP = 1).
	External main system clock			External main system clock input can be disabled (MSTOP = 1).
KC2, KD2, KE2, KF2 (other than KB2)	Internal high-speed oscillation clock	XT1 clock	Stabilization of XT1 oscillation • XTSTART = 0, EXCLKS = 0, OSCSELS = 1, or XTSTART = 1 • After elapse of oscillation stabilization time	Operating current can be reduced by stopping internal high-speed oscillator (RSTOP = 1).
	X1 clock			X1 oscillation can be stopped (MSTOP = 1).
	External main system clock			External main system clock input can be disabled (MSTOP = 1).
	Internal high-speed oscillation clock	External subsystem clock	Enabling input of external clock from EXCLKS pin • XTSTART = 0, EXCLKS = 1, OSCSELS = 1	Operating current can be reduced by stopping internal high-speed oscillator (RSTOP = 1).
	X1 clock			X1 oscillation can be stopped (MSTOP = 1).
	External main system clock			External main system clock input can be disabled (MSTOP = 1).
	XT1 clock, external subsystem clock	Internal high-speed oscillation clock	Oscillation of internal high-speed oscillator and selection of internal high-speed oscillation clock as main system clock • RSTOP = 0, MCS = 0	XT1 oscillation can be stopped or external subsystem clock input can be disabled (OSCSELS = 0).
		X1 clock	Stabilization of X1 oscillation and selection of high-speed system clock as main system clock • MSTOP = 0, OSCSEL = 1, EXCLK = 0 • After elapse of oscillation stabilization time • MCS = 1	• XT1 oscillation can be stopped or external subsystem clock input can be disabled (OSCSELS = 0). • Clock supply to CPU is stopped for 4.06 to 16.12 μs after AMPH has been set to 1.
		External main system clock	Enabling input of external clock from EXCLK pin and selection of high-speed system clock as main system clock • MSTOP = 0, OSCSEL = 1, EXCLK = 1 • MCS = 1	• XT1 oscillation can be stopped or external subsystem clock input can be disabled (OSCSELS = 0). • Clock supply to CPU is stopped for the duration of 160 external clocks from the EXCLK pin after AMPH has been set to 1.

Remark The 78K0/KB2 is not provided with a subsystem clock.

(9) Capture operation

(a) When valid edge of TI00n is specified as count clock

When the valid edge of TI00n is specified as the count clock, the capture register for which TI00n is specified as a trigger does not operate correctly.

(b) Pulse width to accurately capture value by signals input to TI01n and TI00n pins

To accurately capture the count value, the pulse input to the TI00n and TI01n pins as a capture trigger must be wider than two count clocks selected by PRM0n (see **Figure 7-9**).

(c) Generation of interrupt signal

The capture operation is performed at the falling edge of the count clock but the interrupt signals (INTTM00n and INTTM01n) are generated at the rising edge of the next count clock (see **Figure 7-9**).

(d) Note when CRC0n1 (bit 1 of capture/compare control register 0n (CRC0n)) is set to 1

When the count value of the TM0n register is captured to the CR00n register in the phase reverse to the signal input to the TI00n pin, the interrupt signal (INTTM00n) is not generated after the count value is captured. If the valid edge is detected on the TI01n pin during this operation, the capture operation is not performed but the INTTM00n signal is generated as an external interrupt signal. Mask the INTTM00n signal when the external interrupt is not used.

(10) Edge detection

(a) Specifying valid edge after reset

If the operation of the 16-bit timer/event counter 0n is enabled after reset and while the TI00n or TI01n pin is at high level and when the rising edge or both the edges are specified as the valid edge of the TI00n or TI01n pin, then the high level of the TI00n or TI01n pin is detected as the rising edge. Note this when the TI00n or TI01n pin is pulled up. However, the rising edge is not detected when the operation is once stopped and then enabled again.

(b) Sampling clock for eliminating noise

The sampling clock for eliminating noise differs depending on whether the valid edge of TI00n is used as the count clock or capture trigger. In the former case, the sampling clock is fixed to f_{PRS}. In the latter, the count clock selected by PRM0n is used for sampling.

When the signal input to the TI00n pin is sampled and the valid level is detected two times in a row, the valid edge is detected. Therefore, noise having a short pulse width can be eliminated (see **Figure 7-9**).

(11) Timer operation

The signal input to the TI00n/TI01n pin is not acknowledged while the timer is stopped, regardless of the operation mode of the CPU.

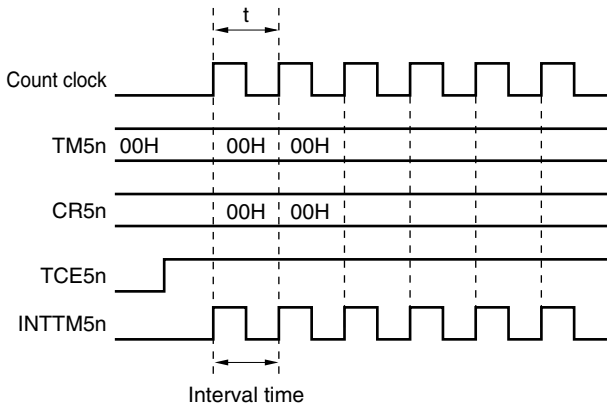
Remarks 1. f_{PRS}: Peripheral hardware clock frequency

2. n = 0: 78K0/KE2 products whose flash memory is less than 32 KB, and 78K0/KB2, 78K0/KC2, 78K0/KD2 products

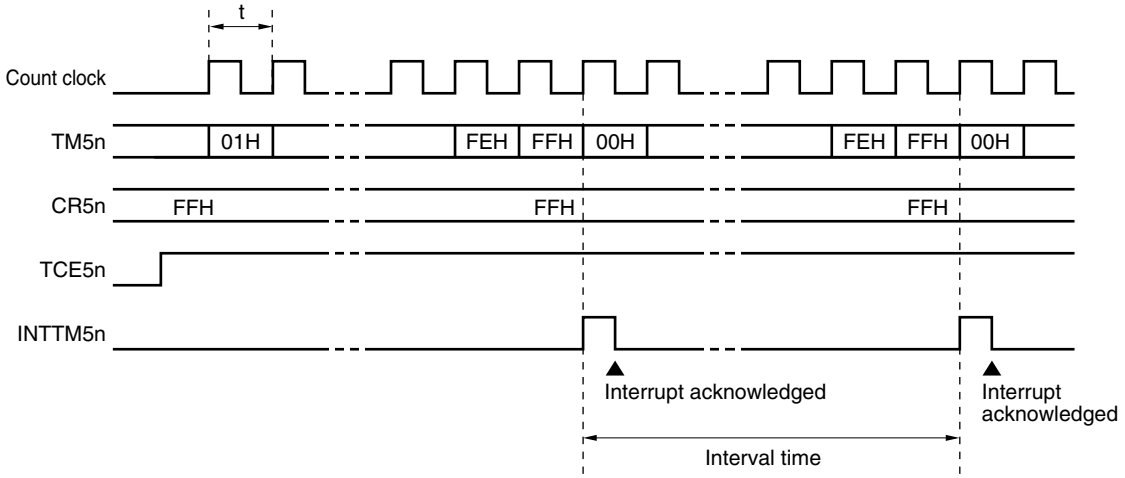
n = 0, 1: 78K0/KE2 products whose flash memory is at least 48 KB, and 78K0/KF2 products

Figure 8-11. Interval Timer Operation Timing (2/2)

(b) When CR5n = 00H



(c) When CR5n = FFH



Remark n = 0, 1

8.4.3 Square-wave output operation

A square wave with any selected frequency is output at intervals determined by the value preset to 8-bit timer compare register 5n (CR5n).

The TO5n pin output status is inverted at intervals determined by the count value preset to CR5n by setting bit 0 (TOE5n) of 8-bit timer mode control register 5n (TMC5n) to 1. This enables a square wave with any selected frequency to be output (duty = 50%).

Setting

<1> Set each register.

- Clear the port output latch (P17 or P33)[Note] and port mode register (PM17 or PM33)[Note] to 0.
- TCL5n: Select the count clock.
- CR5n: Compare value
- TMC5n: Stop the count operation, select the mode in which clear & start occurs on a match of TM5n and CR5n.

LVS5n	LVR5n	Timer Output F/F Status Setting
0	1	Timer output F/F clear (0) (default value of TO5n output: low level)
1	0	Timer output F/F set (1) (default value of TO5n output: high level)

Timer output enabled
(TMC5n = 00001011B or 00000111B)

<2> After TCE5n = 1 is set, the count operation starts.

<3> The timer output F/F is inverted by a match of TM5n and CR5n. After INTTM5n is generated, TM5n is cleared to 00H.

<4> After these settings, the timer output F/F is inverted at the same interval and a square wave is output from TO5n. The frequency is as follows.

- Frequency = 1/2t (N + 1)
  (N: 00H to FFH)

Note 8-bit timer/event counter 50: P17, PM17
8-bit timer/event counter 51: P33, PM33

Caution Do not write other values to CR5n during operation.

Remarks 1. For how to enable the INTTM5n signal interrupt, see **CHAPTER 20 INTERRUPT FUNCTIONS**.
2. n = 0, 1

(3) SO latch

The SO latch is used to retain the SDA0 pin's output level.

(4) Wake-up controller

This circuit generates an interrupt request (INTIIC0) when the address received by this register matches the address value set to slave address register 0 (SVA0) or when an extension code is received.

(5) Prescaler

This selects the sampling clock to be used.

(6) Serial clock counter

This counter counts the serial clocks that are output or input during transmit/receive operations and is used to verify that 8-bit data was transmitted or received.

(7) Interrupt request signal generator

This circuit controls the generation of interrupt request signals (INTIIC0).

An I^2C interrupt request is generated by the following two triggers.

- Falling edge of eighth or ninth clock of the serial clock (set by WTIM0 bit)
- Interrupt request generated when a stop condition is detected (set by SPIE0 bit)

Remark WTIM0 bit: Bit 3 of IIC control register 0 (IICC0)
SPIE0 bit: Bit 4 of IIC control register 0 (IICC0)

(8) Serial clock controller

In master mode, this circuit generates the clock output via the SCL0 pin from a sampling clock.

(9) Serial clock wait controller

This circuit controls the wait timing.

(10) ACK generator, stop condition detector, start condition detector, and ACK detector

These circuits generate and detect each status.

(11) Data hold time correction circuit

This circuit generates the hold time for data corresponding to the falling edge of the serial clock.

(12) Start condition generator

This circuit generates a start condition when the STT0 bit is set to 1.

However, in the communication reservation disabled status (IICRSV bit = 1), when the bus is not released (IICBSY bit = 1), start condition requests are ignored and the STCF bit is set to 1.

(13) Stop condition generator

This circuit generates a stop condition when the SPT0 bit is set to 1.

18.3 Registers to Control Serial Interface IIC0

Serial interface IIC0 is controlled by the following seven registers.

- IIC control register 0 (IICC0)
- IIC flag register 0 (IICF0)
- IIC status register 0 (IICS0)
- IIC clock selection register 0 (IICCL0)
- IIC function expansion register 0 (IICX0)
- Port mode register 6 (PM6)
- Port register 6 (P6)

(1) IIC control register 0 (IICC0)

This register is used to enable/stop I^2C operations, set wait timing, and set other I^2C operations.

IICC0 register is set by a 1-bit or 8-bit memory manipulation instruction. However, set the SPIE0, WTIM0, and ACKE0 bits while IICE0 bit = 0 or during the wait period. These bits can be set at the same time when the IICE0 bit is set from “0” to “1”.

Reset signal generation clears IICC0 to 00H.

Figure 18-7. Format of IIC Flag Register 0 (IICF0)

Address: FFABH After reset: 00H R/W[Note]

Symbol	<7>	<6>	5	4	3	2	<1>	<0>
IICF0	STCF	IICBSY	0	0	0	0	STCEN	IICRSV

STCF	STT0 clear flag
0	Generate start condition
1	Start condition generation unsuccessful: clear STT0 flag

Condition for clearing (STCF = 0)	Condition for setting (STCF = 1)
• Cleared by STT0 = 1 • When IICE0 = 0 (operation stop) • Reset	• Generating start condition unsuccessful and STT0 bit cleared to 0 when communication reservation is disabled (IICRSV = 1).

IICBSY	I^2C bus status flag
0	Bus release status (communication initial status when STCEN = 1)
1	Bus communication status (communication initial status when STCEN = 0)

Condition for clearing (IICBSY = 0)	Condition for setting (IICBSY = 1)
• Detection of stop condition • When IICE0 = 0 (operation stop) • Reset	• Detection of start condition • Setting of IICE0 bit when STCEN = 0

STCEN	Initial start enable trigger
0	After operation is enabled (IICE0 = 1), enable generation of a start condition upon detection of a stop condition.
1	After operation is enabled (IICE0 = 1), enable generation of a start condition without detecting a stop condition.

Condition for clearing (STCEN = 0)	Condition for setting (STCEN = 1)
• Detection of start condition • Reset	• Set by instruction

IICRSV	Communication reservation function disable bit
0	Enable communication reservation
1	Disable communication reservation

Condition for clearing (IICRSV = 0)	Condition for setting (IICRSV = 1)
• Cleared by instruction • Reset	• Set by instruction

Note Bits 6 and 7 are read-only.

Cautions 1. Write to STCEN bit only when the operation is stopped (IICE0 = 0).

2. As the bus release status (IICBSY = 0) is recognized regardless of the actual bus status when STCEN = 1, when generating the first start condition (STT0 = 1), it is necessary to verify that no third party communications are in progress in order to prevent such communications from being destroyed.

3. Write to IICRSV bit only when the operation is stopped (IICE0 = 0).

Remark STT0: Bit 1 of IIC control register 0 (IICC0)
IICE0: Bit 7 of IIC control register 0 (IICC0)

Figure 20-10. Format of Interrupt Mask Flag Registers (MK0L, MK0H, MK1L, MK1H) (78K0/KE2)

Address: FFE4H After reset: FFH R/W

Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>
MK0L	SREMK6	PMK5	PMK4	PMK3	PMK2	PMK1	PMK0	LVIMK

Address: FFE5H After reset: FFH R/W

Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>
MK0H	TMMK010	TMMK000	TMMK50	TMMKH0	TMMKH1	DUALMK0 CSIMK10 STMK0	STMK6	SRMK6

Address: FFE6H After reset: FFH R/W

Symbol	<7>	<6>	<5>	<4>	<3>	<2>	<1>	<0>
MK1L	PMK7	PMK6	WTMK	KRMK	TMMK51	WTIMK	SRMK0	ADMK

Address: FFE7H After reset: FFH R/W

Symbol	7	6	5	4	<3>	<2>	<1>	<0>
MK1H	1	1	1	1	TMMK011[Note]	TMMK001[Note]	CSIMK11[Note]	IICMK0 DMUMK[Note]

XXMKX	Interrupt servicing control
0	Interrupt servicing enabled
1	Interrupt servicing disabled

Note Products whose flash memory is at least 48 KB only.

Caution Be sure to set bits 1 to 7 of MK1H to 1 for the products whose flash memory is less than 32 KB. Be sure to set bits 4 to 7 of MK1H to 1 for the products whose flash memory is at least 48 KB.

(2) When detecting level of input voltage from external input pin (EXLVI)

- When starting operation
  - <1> Mask the LVI interrupt (LVIMK = 1).
  - <2> Set bit 2 (LVISEL) of the low-voltage detection register (LVIM) to 1 (detects level of input voltage from external input pin (EXLVI)).
  - <3> Set bit 7 (LVION) of LVIM to 1 (enables LVI operation).
  - <4> Use software to wait for an operation stabilization time (10 μs (MIN.)).
  - <5> Wait until it is checked that (input voltage from external input pin (EXLVI) ≥ detection voltage (V_{EXLVI} = 1.21 V (TYP.))) by bit 0 (LVIF) of LVIM.
  - <6> Set bit 1 (LVIMD) of LVIM to 1 (generates reset signal when the level is detected).

  Figure 25-6 shows the timing of the internal reset signal generated by the low-voltage detector. The numbers in this timing chart correspond to <1> to <6> above.

  Cautions 1. <1> must always be executed. When LVIMK = 0, an interrupt may occur immediately after the processing in <3>.
  2. If input voltage from external input pin (EXLVI) ≥ detection voltage (V_{EXLVI} = 1.21 V (TYP.)) when LVIMD is set to 1, an internal reset signal is not generated.
  3. Input voltage from external input pin (EXLVI) must be EXLVI < V_{DD}.

- When stopping operation
  Either of the following procedures must be executed.

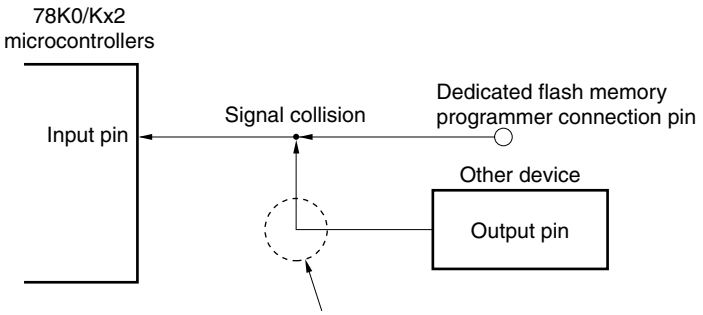
  - When using 8-bit memory manipulation instruction:
    Write 00H to LVIM.

  - When using 1-bit memory manipulation instruction:
    Clear LVIMD to 0 and then LVION to 0.

(1) Signal collision

If the dedicated flash memory programmer (output) is connected to a pin (input) of a serial interface connected to another device (output), signal collision takes place. To avoid this collision, either isolate the connection with the other device, or make the other device go into an output high-impedance state.

Figure 27-7. Signal Collision (Input Pin of Serial Interface)

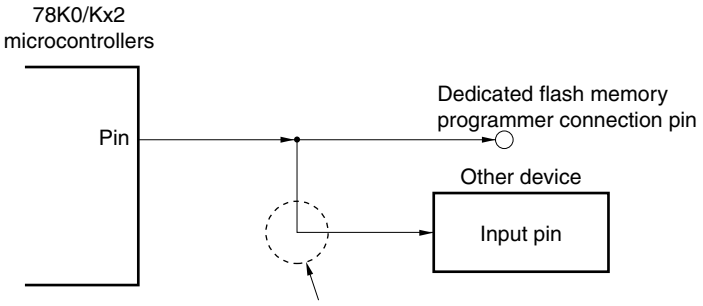


In the flash memory programming mode, the signal output by the device collides with the signal sent from the dedicated flash programmer. Therefore, isolate the signal of the other device.

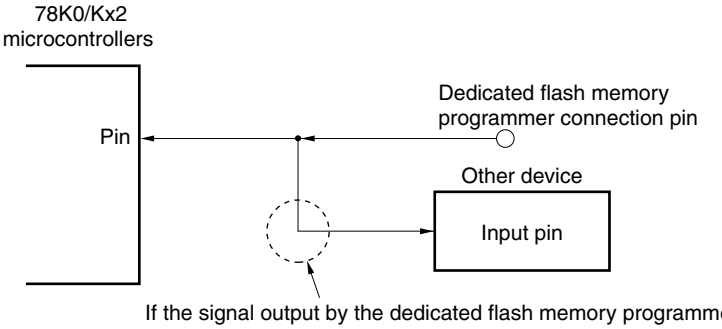
(2) Malfunction of other device

If the dedicated flash memory programmer (output or input) is connected to a pin (input or output) of a serial interface connected to another device (input), a signal may be output to the other device, causing the device to malfunction. To avoid this malfunction, isolate the connection with the other device.

Figure 27-8. Malfunction of Other Device



If the signal output by the 78K0/Kx2 microcontrollers in the flash memory programming mode affects the other device, isolate the signal of the other device.



If the signal output by the dedicated flash memory programmer in the flash memory programming mode affects the other device, isolate the signal of the other device.

Caution The pins mounted depend on the product. Refer to Caution at the beginning of this chapter.

DC Characteristics (2/4)

(T_A = –40 to +85°C, 1.8 V ≤ V_{DD} = EV_{DD} ≤ 5.5 V, AV_{REF} ≤ V_{DD}, V_{SS} = EV_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Input voltage, high (products whose flash memory is at least 48 KB)[Note 1]	V_{IH1}	P02, P12, P13, P15, P40 to P47, P50 to P57, P64 to P67, P121 to P124, P144, P145		0.7V_{DD}		V_{DD}	V
	V_{IH2}	P00, P01, P03 to P06, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140 to P143, EXCLK, EXCLKS, $\overline{\text{RESET}}$		0.8V_{DD}		V_{DD}	V
	V_{IH3}	P20 to P27	AV_{REF} = V_{DD}	0.7AV_{REF}		AV_{REF}	V
	V_{IH4}	P60 to P63		0.7V_{DD}		6.0	V
Input voltage, high (products whose flash memory is less than 32 KB)[Note 2]	V_{IH1}	P02 to P06, P12, P13, P15, P40 to P43, P50 to P53, P121 to P124		0.7V_{DD}		V_{DD}	V
	V_{IH2}	P00, P01, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140, P141, EXCLK, EXCLKS, $\overline{\text{RESET}}$		0.8V_{DD}		V_{DD}	V
	V_{IH3}	P20 to P27	AV_{REF} = V_{DD}	0.7AV_{REF}		AV_{REF}	V
	V_{IH4}	P60 to P63		0.7V_{DD}		6.0	V
Input voltage, low (products whose flash memory is at least 48 KB)[Note 1]	V_{IL1}	P02, P12, P13, P15, P40 to P47, P50 to P57, P60 to P67, P121 to P124, P144, P145		0		0.3V_{DD}	V
	V_{IL2}	P00, P01, P03 to P06, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140 to P143, EXCLK, EXCLKS, $\overline{\text{RESET}}$		0		0.2V_{DD}	V
	V_{IL3}	P20 to P27	AV_{REF} = V_{DD}	0		0.3AV_{REF}	V
Input voltage, low (products whose flash memory is less than 32 KB)[Note 2]	V_{IL1}	P02 to P06, P12, P13, P15, P40 to P43, P50 to P53, P60 to P63, P121 to P124		0		0.3V_{DD}	V
	V_{IL2}	P00, P01, P10, P11, P14, P16, P17, P30 to P33, P70 to P77, P120, P140, P141, EXCLK, EXCLKS, $\overline{\text{RESET}}$		0		0.2V_{DD}	V
	V_{IL3}	P20 to P27	AV_{REF} = V_{DD}	0		0.3AV_{REF}	V
Output voltage, high	V_{OH1}	P00 to P06, P10 to P17, P30 to P33, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P120, P130, P140 to P145	4.0 V ≤ V_{DD} ≤ 5.5 V, I_{OH1} = –3.0 mA	V_{DD} – 0.7			V
			2.7 V ≤ V_{DD} < 4.0 V, I_{OH1} = –2.5 mA	V_{DD} – 0.5			V
			1.8 V ≤ V_{DD} < 2.7 V, I_{OH1} = –1.0 mA	V_{DD} – 0.5			V
	V_{OH2}	P20 to P27	AV_{REF} = V_{DD}, I_{OH2} = –100 μA	V_{DD} – 0.5			V
		P121 to P124	I_{OH2} = –100 μA	V_{DD} – 0.5			V

Notes 1. Supported products: 78K0/KD2 and 78K0/KE2 whose flash memory is at least 48 KB, and 78K0/KF2

2. Supported products: 78K0/KD2 and 78K0/KE2 whose flash memory is less than 32 KB, 78K0/KB2, and 78K0/KC2

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

Caution The pins mounted depend on the product. Refer to Caution 2 at the beginning of this chapter.

(1) Basic operation (2/2)

(T_A = –40 to +110°C, 2.7 V ≤ V_{DD} = EV_{DD} ≤ 5.5 V, AV_{REF} ≤ V_{DD}, V_{SS} = EV_{SS} = AV_{SS} = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
External subsystem clock frequency[Note 1]	f_{EXCLKS}		32	32.768	35	kHz
External subsystem clock input high-level width, low-level width[Note 1]	$t_{EXCLKSH}$, $t_{EXCLKSL}$		12			μs
TI000, TI010, TI001, TI011 input high-level width, low-level width	t_{TIH0}, t_{TIL0}	4.0 V ≤ V_{DD} ≤ 5.5 V	$2/f_{sam}$ + 0.1[Note 2]			μs
		2.7 V ≤ V_{DD} < 4.0 V	$2/f_{sam}$ + 0.2[Note 2]			μs
TI50, TI51 input frequency	f_{TI5}				10	MHz
TI50, TI51 input high-level width, low-level width	t_{TIH5}, t_{TIL5}		50			ns
Interrupt input high-level width, low-level width	t_{INTH}, t_{INTL}		1			μs
Key interrupt input low-level width	t_{KR}		250			ns
$\overline{\text{RESET}}$ low-level width	t_{RSL}		10			μs

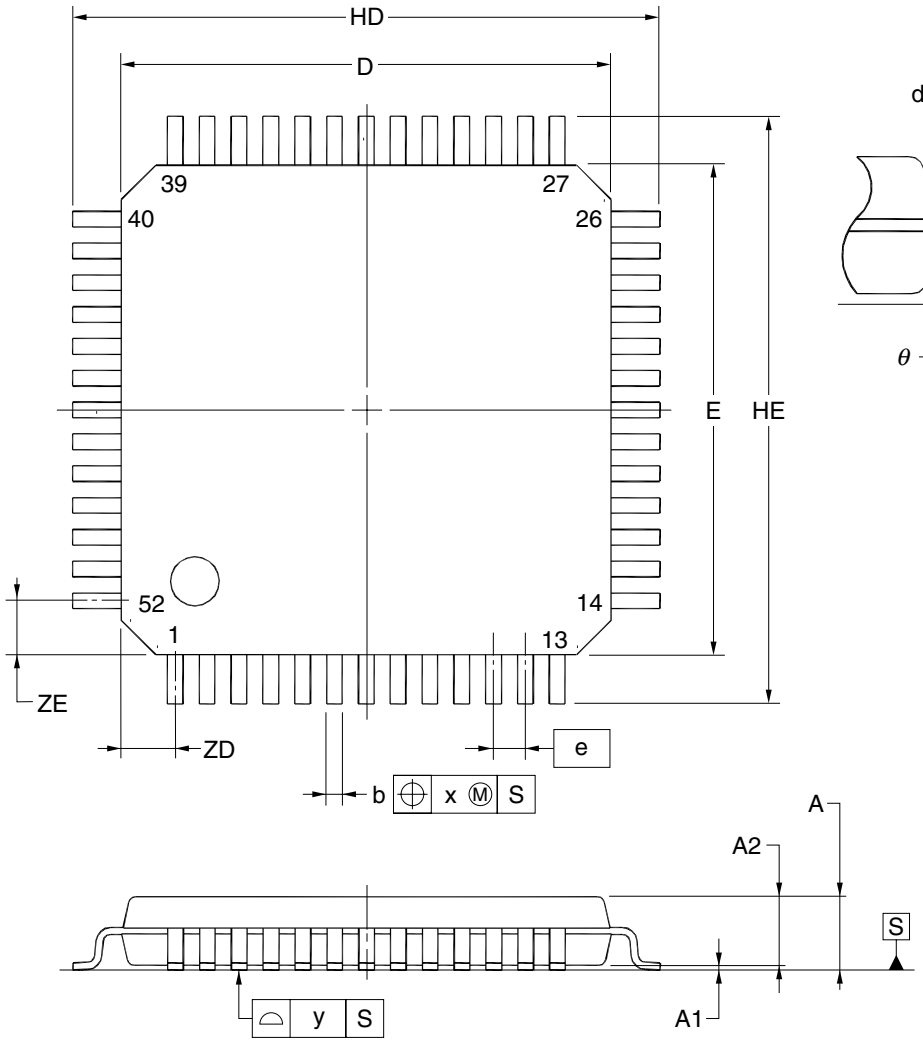
Notes 1. The 78K0/KB2 is not provided with a subsystem clock.

2. Selection of f_{sam} = f_{PRS}, $f_{PRS}/4$, $f_{PRS}/256$, or f_{PRS}, $f_{PRS}/16$, $f_{PRS}/64$ is possible using bits 0 and 1 (PRM000, PRM001 or PRM010, PRM011) of prescaler mode registers 00 and 01 (PRM00, PRM01). Note that when selecting the TI000 or TI001 valid edge as the count clock, f_{sam} = f_{PRS}.

34.3 78K0/KD2

- μPD78F0521GB-UET-A, 78F0522GB-UET-A, 78F0523GB-UET-A, 78F0524GB-UET-A, 78F0525GB-UET-A, 78F0526GB-UET-A, 78F0527GB-UET-A, 78F0527DGB-UET-A

52-PIN PLASTIC LQFP(10x10)



(UNIT:mm)

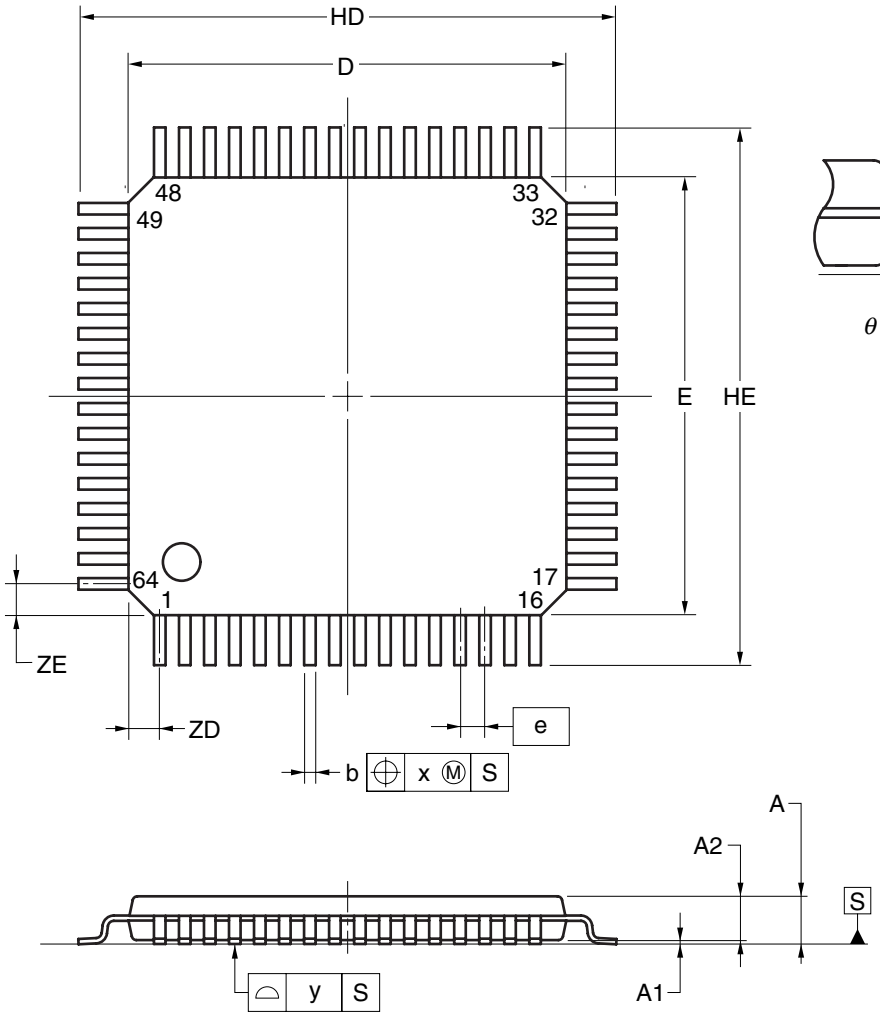
ITEM	DIMENSIONS
D	10.00±0.20
E	10.00±0.20
HD	12.00±0.20
HE	12.00±0.20
A	1.60 MAX.
A1	0.10±0.05
A2	1.40±0.05
A3	0.25
b	$0.32^{+0.08}_{-0.07}$
c	$0.145^{+0.055}_{-0.045}$
L	0.50
Lp	0.60±0.15
L1	1.00±0.20
θ	$3^{\circ}{}^{+5^{\circ}}_{-3^{\circ}}$
e	0.65
x	0.13
y	0.10
ZD	1.10
ZE	1.10

P52GB-65-UET-1

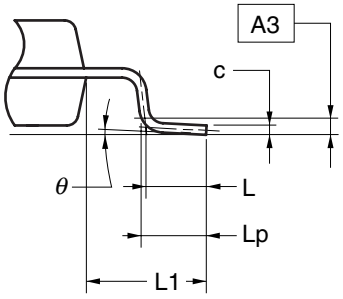
NOTE
Each lead centerline is located within 0.13 mm of its true position at maximum material condition.

- μPD78F0531GC(A)-GAL-AX, 78F0532GC(A)-GAL-AX, 78F0533GC(A)-GAL-AX, 78F0534GC(A)-GAL-AX, 78F0535GC(A)-GAL-AX, 78F0536GC(A)-GAL-AX, 78F0537GC(A)-GAL-AX
- μPD78F0531GC(A2)-GAL-AX, 78F0532GC(A2)-GAL-AX, 78F0533GC(A2)-GAL-AX, 78F0534GC(A2)-GAL-AX, 78F0535GC(A2)-GAL-AX, 78F0536GC(A2)-GAL-AX, 78F0537GC(A2)-GAL-AX
- μPD78F0531AGC-GAL-AX, 78F0532AGC-GAL-AX, 78F0533AGC-GAL-AX, 78F0534AGC-GAL-AX, 78F0535AGC-GAL-AX, 78F0536AGC-GAL-AX, 78F0537AGC-GAL-AX, 78F0537DAGC-GAL-AX
- μPD78F0531AGCA-GAL-G, 78F0532AGCA-GAL-G, 78F0533AGCA-GAL-G, 78F0534AGCA-GAL-G, 78F0535AGCA-GAL-G, 78F0536AGCA-GAL-G, 78F0537AGCA-GAL-G
- μPD78F0531AGCA2-GAL-G, 78F0532AGCA2-GAL-G, 78F0533AGCA2-GAL-G, 78F0534AGCA2-GAL-G, 78F0535AGCA2-GAL-G, 78F0536AGCA2-GAL-G, 78F0537AGCA2-GAL-G

64-PIN PLASTIC LQFP (14x14)



detail of lead end



(UNIT:mm)

ITEM	DIMENSIONS
D	14.00±0.20
E	14.00±0.20
HD	17.20±0.20
HE	17.20±0.20
A	1.70 MAX.
A1	0.125±0.075
A2	1.40±0.05
A3	0.25
b	$0.35^{+0.08}_{-0.04}$
c	$0.125^{+0.075}_{-0.025}$
L	0.80
Lp	0.886±0.15
L1	1.60±0.20
θ	$3^{\circ}{}^{+5^{\circ}}_{-3^{\circ}}$
e	0.80
x	0.20
y	0.10
ZD	1.00
ZE	1.00

P64GC-80-GAL

NOTE
Each lead centerline is located within 0.20 mm of its true position at maximum material condition.

(26/30)

Chapter	Classification	Function	Details of Function	Cautions	Page
Chapter 24	Soft	Power-on-clear circuit	In 2.7 V/1.59 V POC mode	A voltage oscillation stabilization time of 1.93 to 5.39 ms is required after the supply voltage reaches 1.59 V (TYP.). If the supply voltage rises from 1.59 V (TYP.) to 2.7 V (TYP.) within 1.93 ms, the power supply oscillation stabilization time of 0 to 5.39 ms is automatically generated before reset processing.	p. 695 ☐
			Cautions for power-on-clear circuit	In a system where the supply voltage (V_{DD}) fluctuates for a certain period in the vicinity of the POC detection voltage (V_{POC}), the system may be repeatedly reset and released from the reset status. In this case, the time from release of reset to the start of the operation of the microcontroller can be arbitrarily set by taking the following action.	p. 696 ☐
Chapter 25	Soft	Low-voltage detector	LVIM: Low-voltage detection register	To stop LVI, follow either of the procedures below. • When using 8-bit memory manipulation instruction: Write 00H to LVIM. • When using 1-bit memory manipulation instruction: Clear LVION to 0.	p. 700 ☐
	Hard			Input voltage from external input pin (EXLVI) must be EXLVI < V_{DD}.	p. 700 ☐
	Soft			When using LVI as an interrupt, if LVION is cleared (0) in a state below the LVI detection voltage, an INTLVI signal is generated and LVIIF becomes 1.	p. 701 ☐
			LVIM and LVIS	With the conventional-specification products (μPD78F05xx and 78F05xxD), after an LVI reset has been generated, do not write values to LVIS and LVIM when LVION = 1.	p. 701 ☐
			LVIS: Low-voltage detection level selection register	Be sure to clear bits 4 to 7 to "0".	p. 701 ☐
				Do not change the value of LVIS during LVI operation.	p. 701 ☐
				When an input voltage from the external input pin (EXLVI) is detected, the detection voltage (V_{EXLVI} = 1.21 V (TYP.)) is fixed. Therefore, setting of LVIS is not necessary.	p. 701 ☐
				With the conventional-specification products (μPD78F05xx and 78F05xxD), after an LVI reset has been generated, do not write values to LVIS and LVIM when LVION = 1.	p. 701 ☐
			When used as reset (When detecting level of supply voltage (V_{DD}))	<1> must always be executed. When LVIMK = 0, an interrupt may occur immediately after the processing in <4>.	p. 703 ☐
				If supply voltage (V_{DD}) ≥ detection voltage (V_{LVI}) when LVIMD is set to 1, an internal reset signal is not generated.	p. 703 ☐
			When used as reset (When detecting level of input voltage from external input pin (EXLVI))	<1> must always be executed. When LVIMK = 0, an interrupt may occur immediately after the processing in <3>.	p. 706 ☐
				If input voltage from external input pin (EXLVI) ≥ detection voltage (V_{EXLVI} = 1.21 V (TYP.)) when LVIMD is set to 1, an internal reset signal is not generated.	p. 706 ☐
	Hard			Input voltage from external input pin (EXLVI) must be EXLVI < V_{DD}.	p. 706 ☐
			When used as interrupt (When detecting level of input voltage from external input pin (EXLVI))	Input voltage from external input pin (EXLVI) must be EXLVI < V_{DD}.	p. 711 ☐
	Soft		Cautions for low-voltage detector	In a system where the supply voltage (V_{DD}) fluctuates for a certain period in the vicinity of the LVI detection voltage (V_{LVI}), the operation is as follows depending on how the low-voltage detector is used. (1) When used as reset The system may be repeatedly reset and released from the reset status. In this case, the time from release of reset to the start of the operation of the microcontroller can be arbitrarily set by taking action (1) below. (2) When used as interrupt Interrupt requests may be frequently generated. Take (b) of action (2) below.	p. 713 ☐
Chapter 26	Soft	Option byte	0082H, 0083H/1082H, 1083H	Be sure to set 00H to 0082H and 0083H (0082H/1082H and 0083H/1083H when the boot swap function is used).	p. 716 ☐
			0080H/1080H	Set a value that is the same as that of 0080H to 1080H because 0080H and 1080H are switched during the boot swap operation.	p. 716 ☐

SALES OFFICES Renesas Electronics Corporation http://www.renesas.com

Refer to "http://www.renesas.com/" for the latest and detailed information.

Renesas Electronics America Inc.
2880 Scott Boulevard Santa Clara, CA 95050-2554, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited
1101 Nicholson Road, Newmarket, Ontario L3Y 9C3, Canada
Tel: +1-905-898-5441, Fax: +1-905-898-3220

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH
Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-211-65030, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
7th Floor, Quantum Plaza, No.27 ZhiChunLu Haidian District, Beijing 100083, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 204, 205, AZIA Center, No.1233 Lujiazui Ring Rd., Pudong District, Shanghai 200120, China
Tel: +86-21-5877-1818, Fax: +86-21-6887-7858 / -7898

Renesas Electronics Hong Kong Limited
Unit 1601-1613, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2886-9318, Fax: +852 2886-9022/9044

Renesas Electronics Taiwan Co., Ltd.
7F, No. 363 Fu Shing North Road Taipei, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.
1 harbourFront Avenue, #06-10, keppel Bay Tower, Singapore 098632
Tel: +65-6213-0200, Fax: +65-6278-8001

Renesas Electronics Malaysia Sdn.Bhd.
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics Korea Co., Ltd.
11F., Samik Lavied' or Bldg., 720-2 Yeoksam-Dong, Kangnam-Ku, Seoul 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141

Colophon 1.0